

# Electro-deposited Copper Foil for PCB

## “JTCS-P1”

- Available in multiple thickness.
- Arsenic free treatment.
- Excellent fine line etching performance.
- IPC grade 3 foil.

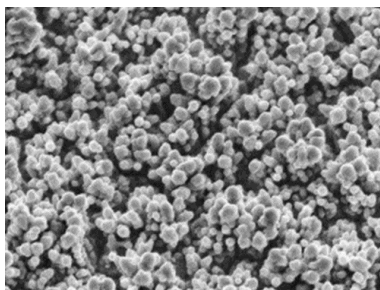
### Typical properties of copper foil JTCS-P1

Thickness	μm	9μ	12μ	18μ	35μ
Area Weight	g/m <sup>2</sup>	76	105	153	284
Tensile Strength at Room Temp	kg/mm <sup>2</sup>	40	40	40	37
Elongation at Room Temp	%	4	9	11	16
Elongation at 180°C	%	3	3	2	2
Treated Side Roughness Rz (IPC / JIS Standard)	μm	2 / 3	3 / 4	3 / 4	5 / 6
Untreated Side Roughness Ra (IPC / JIS Standard)	μm	0.2	0.2	0.2	0.2
Untreated Side Roughness Rz (IPC / JIS Standard)	μm	1.2 / 1.4	1.2 / 1.4	1.2 / 1.4	1.2 / 1.4
Peel Strength As Received	kg/cm	1.0	1.2	1.4	1.9
Peel Strength After Solder	kg/cm	0.9	1.1	1.3	1.9

Representative data as reference

### Matte side SEM photo (x5000)

JTCS-P1 9μm



JTCS-P1 12μm

